



Click [here](#) for the 3D model.

#### General Information

|             |  |
|-------------|--|
| Series      | Array Comm COG Flex                          |
| Style       | SMD Array                                    |
| Description | SMD, MLCC, Array, Flex Termination, Class II |
| RoHS        | Yes  |
| Termination | Flexible Termination                         |
| AEC-Q200    | No   |
| Chip Size   | 0612   |
| MSL         | 1  |

#### Dimensions

|   |                 |
|---|-----------------|
| L | 1.6mm +/-0.2mm  |
| W | 3.2mm +/-0.2mm  |
| T | 0.8mm +/-0.10mm |

#### Packaging Specifications

|                    |                        |
|--------------------|------------------------|
| Packaging          | T&R, 180mm, Paper Tape |
| Packaging Quantity | 4000                   |

#### Specifications

|                         |                    |
|-------------------------|--------------------|
| Capacitance             | 390 pF             |
| Capacitance Tolerance   | 10%                |
| Voltage DC              | 25 VDC             |
| Temperature Range       | -55/+125°C         |
| Temperature Coefficient | COG                |
| Dissipation Factor      | 0.1% 1 MHz 1.0Vrms |
| Insulation Resistance   | 100 GOhms          |